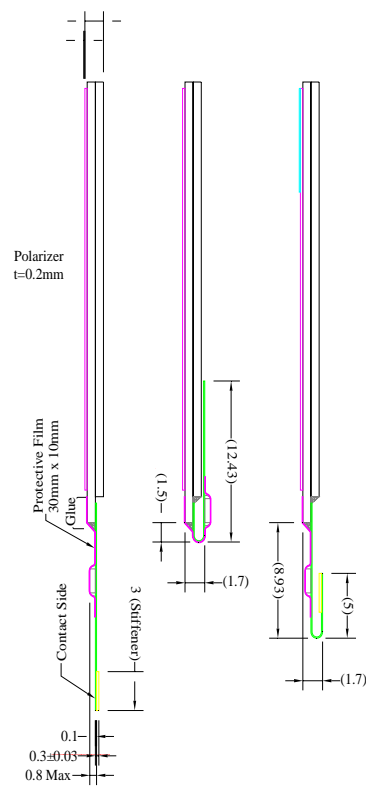
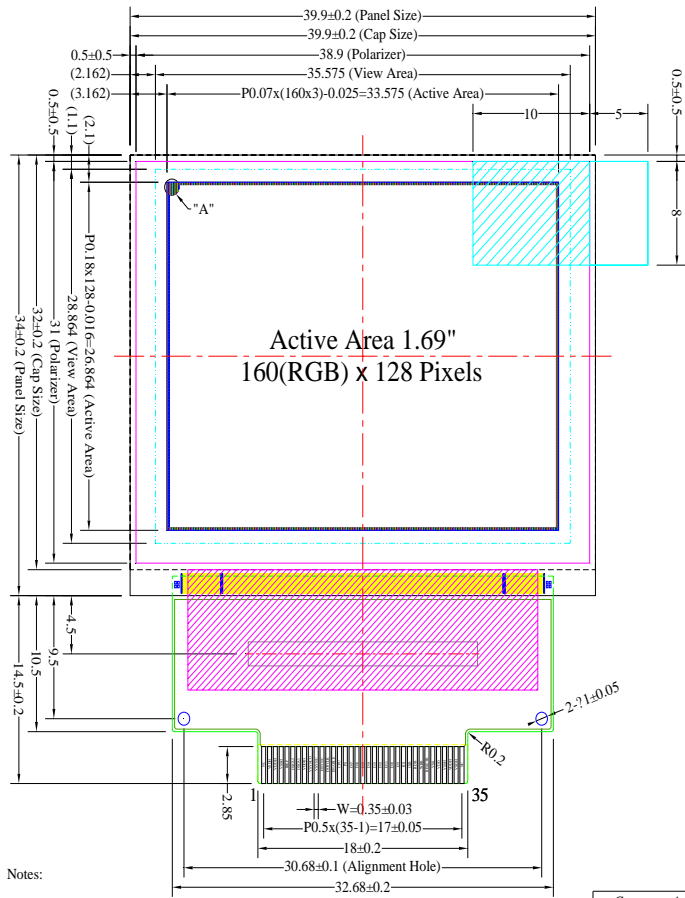




MODULE NO.: MI160128AO

Ver A

Item	Date	Remark
A	20060419	Original Drawing
B	20060714	Modify Module thickness dimension



Pin	Symbol
1	NC
2	VSDH
3	VDDH
4	VSSH
5	JREF
6	OSCA2
7	OSCA1
8	VDDIO
9	VSYNCO
10	VSYNC
11	HSYNC
12	DOTCLK
13	ENABLE
14	CPU
15	PS
16	D17
17	D16
18	D15
19	D14
20	D13
21	D12
22	D11
23	D10
24	D9
25	RS
26	CSB
27	RDB
28	WRB
29	RESETB
30	VSS
31	VDD
32	VSSH
33	VDDH
34	VSDH
35	NC

Detail "A" (20:1) Display Pattern

- Notes:
1. Driver IC: SEPS525
  2. Die Size: 19660um x 1850um
  3. COF Number: SEPS525-F00
  4. Interface: 6-/8-/9/ bit 68XX/80XX Parallel, 6bit-RGB I/F, 4-wire SPI
  5. General Tolerance: ±0.30
  6. The total thickness (1.70 Max) is without Polarizer protective film & Remove Tape. The actual assembled total thickness with above materials should be 1.85 Max

Customer Approval Signature		MULTI-INNO TECHNOLOGY CO.,LTD.						Drawing Number		Rev.	
										B	
Unless Otherwise Specified		Unit		Title		MI160128AO					
		mm									
General Roughness		±									
Tolerance				Drawn		Panel / E.		E.E		PM	
Dimension		±0.3		By							
Angle		±1		Date		20060714		20060714		20060714	
								Scale		Sheet	
								1:1		1 of 1	
										Size	
										A3	

Material Soda Lime / Polyimide